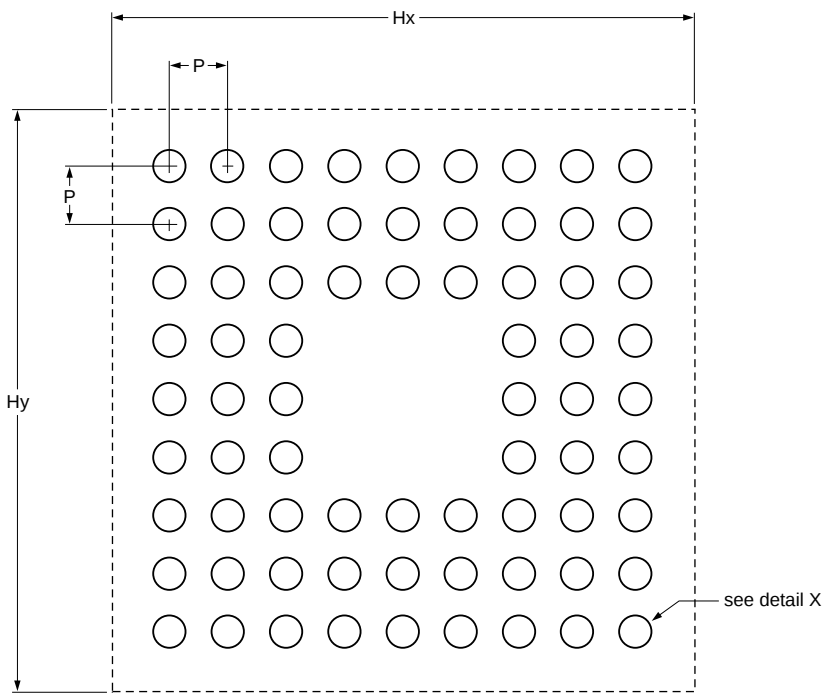


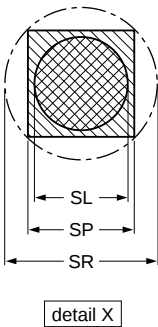
Footprint information for reflow soldering of TFBGA64 package

SOT543-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- - - - - solder resist



DIMENSIONS in mm

| P    | SL    | SP    | SR    | Hx    | Hy    |
|------|-------|-------|-------|-------|-------|
| 0.50 | 0.275 | 0.300 | 0.425 | 6.500 | 6.500 |